



## Product Change Notification: BLAS-15VJAK507

**Date:**

11-Sep-2025

**Product Category:**

Linear Regulators

**Notification Subject:**

CCB 7594 Initial Notice: Qualification of ATP7 as an additional assembly site for selected MIC94355, MIC94305, MIC94325 and MIC94345 device families available in 6L UDFN (1.6x1.6x0.6mm) package.

**Affected CPNs:**

[\*\*BLAS-15VJAK507\\_Affected\\_CPN\\_09112025.pdf\*\*](#)

[\*\*BLAS-15VJAK507\\_Affected\\_CPN\\_09112025.csv\*\*](#)

**PCN Status:** Initial Notification

**PCN Type:** Manufacturing Change

**Microchip Parts Affected:** Please open one of the files found in the Affected CPNs section.  
Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

**Description of Change:** Qualification of ATP7 as an additional assembly site for selected MIC94355, MIC94305, MIC94325 and MIC94345 device families available in 6L UDFN (1.6x1.6x0.6mm) package.

**Pre and Post Summary Changes:**

	<b>Pre Change</b>	<b>Post Change</b>	
<b>Assembly Site</b>	Unisem Chengdu Co.,Ltd. (UNIC)	Unisem Chengdu Co.,Ltd. (UNIC)	Amkor Technology Philippines (P3/P4), INC. (ATP7)
<b>Wire Material</b>	Au	Au	CuPdAu
<b>Die Attach Material</b>	8290	8290	CDF215

<b>Molding Compound Material</b>	G770HP	G770HP	G631BQF
<b>Lead-Frame Material</b>	C194	C194	C7025
<b>Lead-Frame Design</b>	See Pre and Post Change for Comparison.		

**Impacts to Datasheet:** None

**Change Impact:** None

**Reason for Change:** To improve on-time delivery performance by qualifying ATP7 as an additional assembly site.

**Change Implementation Status:** In Progress

**Estimated Qualification Completion Date:** November 2025

**Note:** Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

**Timetable Summary:**

	May 2025					>	November 2025					
Work Week	18	19	20	21	22		44	45	46	47	48	49
Initial PCN Issue Date				x								
Qual Report Availability												x
Final PCN Issue Date												x

**Method to Identify Change:** Traceability Code

**Qualification Plan:** Please open the attachments included with this PCN labeled as PCN\_#\_Qual\_Plan.

**Revision History:** May 19, 2025: Issued initial notification.

September 11, 2025: Re-issued initial notification to update the die attach material from ATB-F125E to CDF215.

**Note:** The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

## **Attachments:**

[\*\*PCN\\_BLAS-15VJAK507\\_Pre\\_and Post Change Summary.pdf\*\*](#)

[\*\*PCN\\_BLAS-15VJAK507\\_Qual Plan.pdf\*\*](#)

Please contact your local [\*\*Microchip sales office\*\*](#) with questions or concerns regarding this notification.

## **Terms and Conditions:**

If you wish to receive Microchip PCNs via email please register for our PCN email service at our [\*\*PCN home page\*\*](#) select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the [\*\*PCN FAQ\*\*](#) section.

If you wish to change your PCN profile, including opt out, please go to the [\*\*PCN home page\*\*](#) select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.